

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.65613	100.0	0.77
			<b>Subtotal</b>	<b>0.65613</b>	<b>100</b>	<b>0.77</b>
Wire	Impurity	Non hazardous		0	0.01	0
	Pure metal	Copper (Cu)	7440-50-8	0.02929	99.99	0.03438
			<b>Subtotal</b>	<b>0.02929</b>	<b>100</b>	<b>0.03438</b>
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02601	0.05	0.03053
	Copper alloy	Zinc (Zn)	7440-66-6	0.05202	0.1	0.06105
	Copper alloy	Iron (Fe)	7439-89-6	1.1965	2.3	1.40415
	Copper alloy	Copper (Cu)	7440-50-8	50.74738	97.55	59.55427
			<b>Subtotal</b>	<b>52.02191</b>	<b>100</b>	<b>61.05</b>
Post-plating	Lead alloy	Tin (Sn)	7440-31-5	0.48571	100.0	0.57
			<b>Subtotal</b>	<b>0.48571</b>	<b>100</b>	<b>0.57</b>
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	0.68932	1.5	0.80895
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	4.36571	9.5	5.12335
	Filler	Silica fused	60676-86-0	40.44025	88.0	47.4584
	Carbon Black	Carbon black	1333-86-4	0.45955	1.0	0.5393
			<b>Subtotal</b>	<b>45.95483</b>	<b>100</b>	<b>53.93</b>
Die Attach		Aromatic Polyester Resin	60088-52-0	0.0213	2.5	0.025
		Paraffin wax	8002-74-2	0.05965	7.0	0.07
		Epoxy resin system		0.17042	20.0	0.2
		Silver (Ag)	7440-22-4	0.60074	70.5	0.705
			<b>Subtotal</b>	<b>0.85211</b>	<b>100</b>	<b>1</b>
			<b>Total</b>	<b>99.99998</b>	<b>100</b>	<b>117.35438</b>

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